

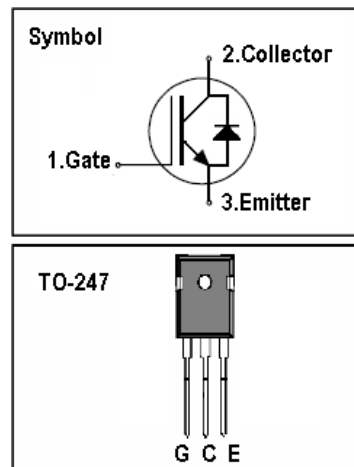


Features

- 650V 75A, $V_{CE(sat)(typ.)} = 2.3V$
- Field Stop IGBT Technology
- 10 μ s Short Circuit Capability
- Square RBSOA
- Positive VCE (on) Temperature Coefficient.

General Description

LGE's IGBTs offer lower losses and higher energy for application such as motor drive ,UPS, inverter and other soft switching applications.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	30	V
I_C	Continuous Collector Current ($T_C=25\text{ }^{\circ}\text{C}$)	150	A
	Continuous Collector Current ($T_C=100\text{ }^{\circ}\text{C}$)	75	A
I_{CM}	Pulsed Collector Current (Note 1)	300	A
I_F	Diode Continuous Forward Current ($T_C=100\text{ }^{\circ}\text{C}$)	60	A
I_{FM}	Diode Maximum Forward Current (Note 1)	240	A
t_{sc}	Short Circuit Withstand Time	10	us
I_{sc}	Short Circuit Current	410	A
P_D	Maximum Power Dissipation ($T_C=25\text{ }^{\circ}\text{C}$)	286	W
P_D	Maximum Power Dissipation ($T_C=100\text{ }^{\circ}\text{C}$)	71	W
T_J	Operating Junction Temperature Range	-55 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$

Thermal Characteristics

Symbol	Parameter	Max.	Units
R_{thj-c}	Thermal Resistance, Junction to case for IGBT	0.35	$^{\circ}\text{C}/\text{W}$
R_{thj-c}	Thermal Resistance, Junction to case for Diode	0.45	$^{\circ}\text{C}/\text{W}$
R_{thj-a}	Thermal Resistance, Junction to Ambient	40	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics (T_C=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	650	-	-	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} = 600V, V _{GE} = 0V	-	-	50	uA
I _{GES}	Gate Leakage Current, Forward	V _{GE} = 30V, V _{CE} = 0V	-	-	200	nA
	Gate Leakage Current, Reverse	V _{GE} = -30V, V _{CE} = 0V	-	-	-200	nA
V _{GE(th)}	Gate Threshold Voltage	V _{GE} = V _{CE} , I _C = 0.75mA	4.0	-	6	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} = 15V, I _C = 75A	-	2.3	2.5	V
Q _g	Total Gate Charge	V _{CC} = 400V V _{GE} = 15V I _C = 75A	-	192	-	nC
Q _{ge}	Gate-Emitter Charge		-	27	-	nC
Q _{gc}	Gate-Collector Charge		-	105	-	nC
t _{d(on)}	Turn-on Delay Time	V _{CC} = 400V V _{GE} = 15V I _C = 75A R _G = 12Ω Inductive Load T _C = 25 °C	-	38	-	ns
t _r	Turn-on Rise Time		-	123	-	ns
t _{d(off)}	Turn-off Delay Time		-	183	-	ns
t _f	Turn-off Fall Time		-	91	-	ns
E _{on}	Turn-on Switching Loss		-	3.5	-	mJ
E _{off}	Turn-off Switching Loss		-	2.4	-	mJ
C _{ies}	Input Capacitance	V _{CE} = 25V V _{GE} = 0V f = 1MHz	-	2.54	-	nF
C _{oes}	Output Capacitance		-	230	-	pF
C _{res}	Reverse Transfer Capacitance		-	60	-	pF
R _{Gint}	Integrated gate resistor	f = 1M; V _{pp} = 1V		1.6	-	Ω

Electrical Characteristics of Diode (T_C=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _F	Diode Forward Voltage	I _F = 60A	-	1.5	-	V
t _{rr}	Diode Reverse Recovery Time	V _{CE} = 400V I _F = 60A dI _F /dt = 500A/us	-	115	-	ns
I _{rrm}	Diode peak Reverse Recovery Current		-	16.0	-	A
Q _{rr}	Diode Reverse Recovery Charge		-	0.88	-	uC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



Typical Performance Characteristics

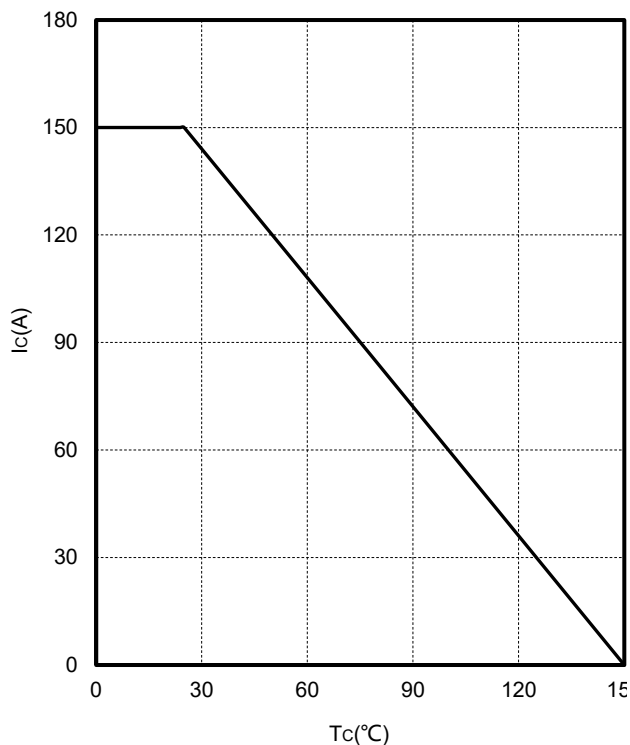


Fig 1. DC Collector current as a function of case temperature ($V_{GE} \geq 15V$, $T_j \leq 150^\circ C$)

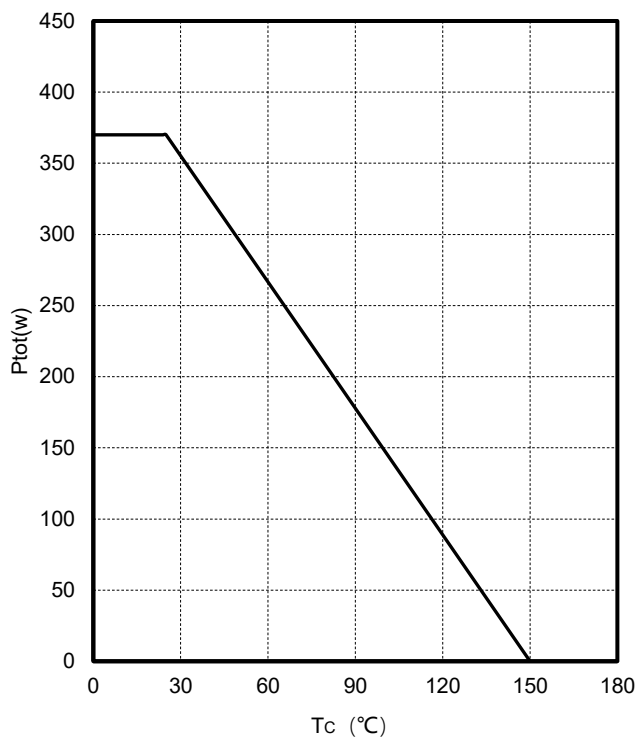


Fig 2. Power dissipation as a function of case temperature ($T_j \leq 150^\circ C$)

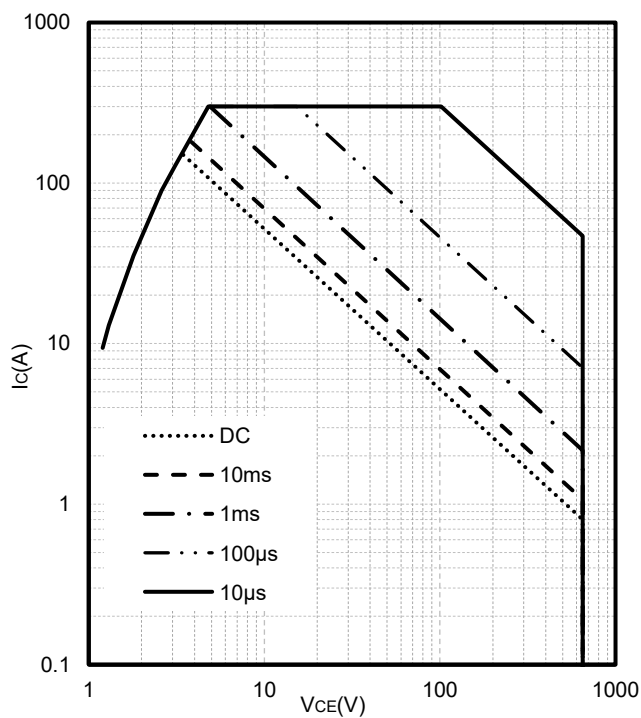


Fig 3. IGBT Forward safe operation area

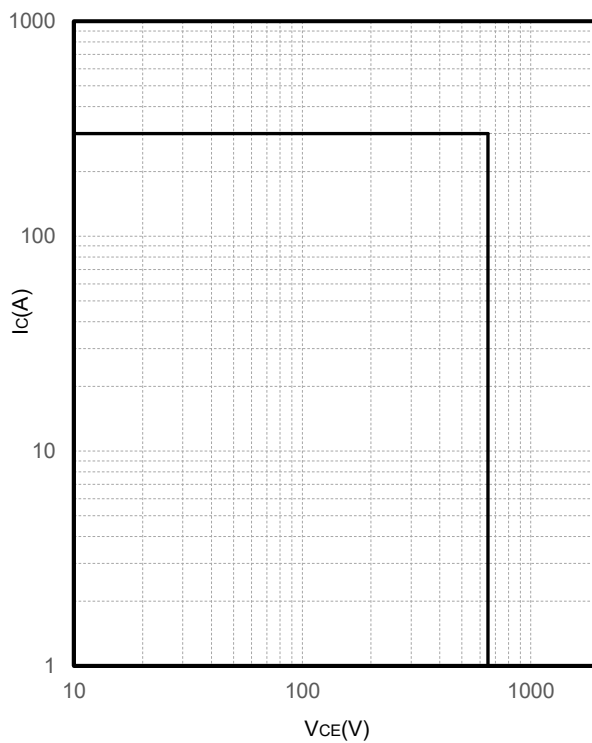


Fig 4. IGBT Reverse safe operation area

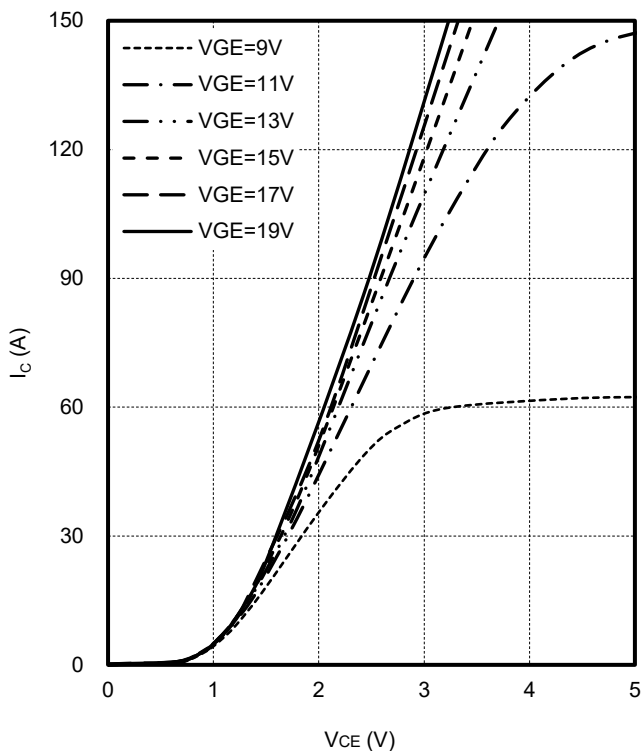


Fig 5. Typical output characteristic ($T_j=25^\circ\text{C}$)

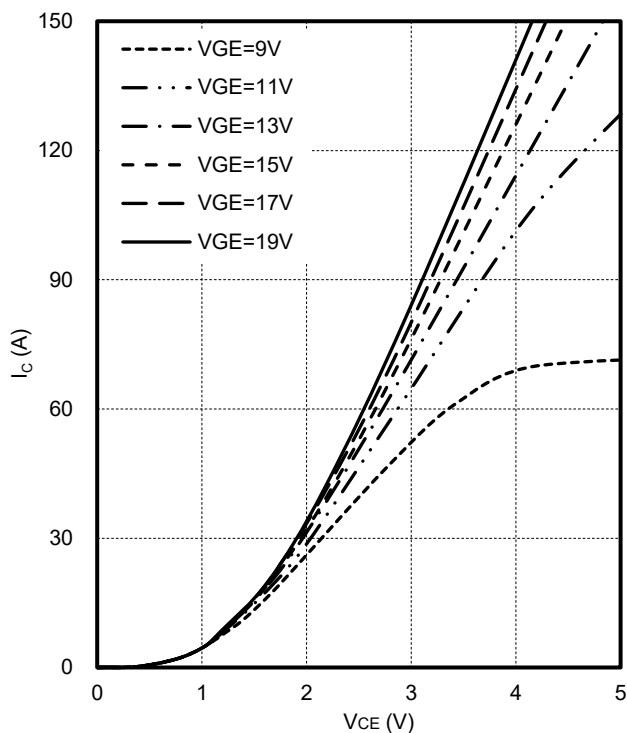


Fig 6. Typical output characteristic ($T_j=125^\circ\text{C}$)

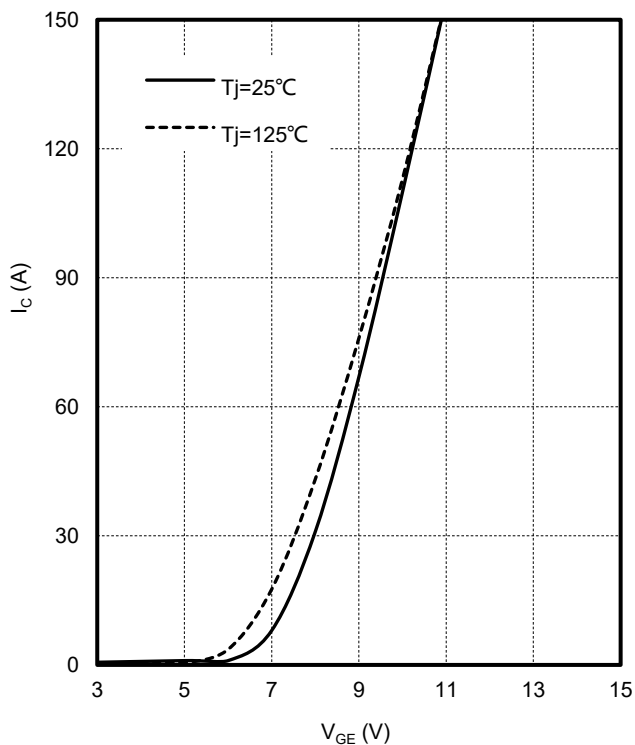


Fig 7. Transfer characteristic IGBT,
 $I_C=f(V_{GE}), V_{CE}=20\text{V}$

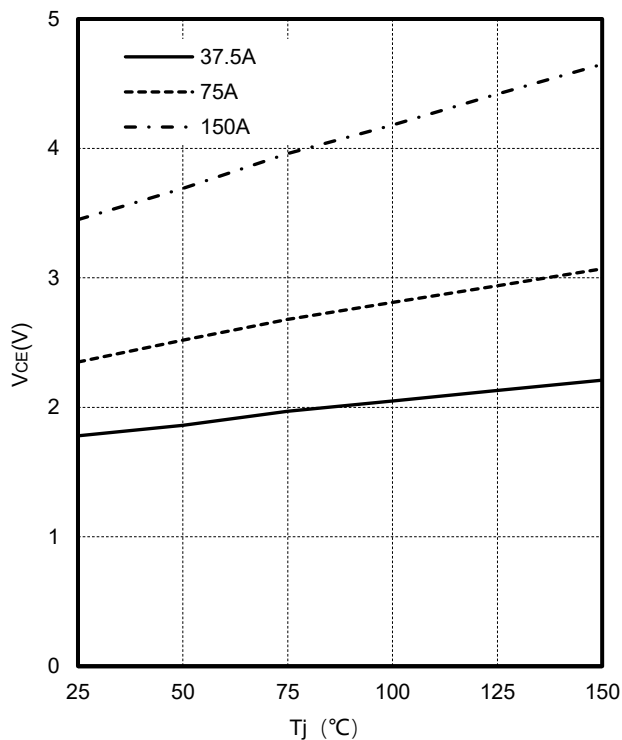


Fig 8. Typical collector-emitter saturation voltage
as a function of junction temperature,
 $I_{GBT} V_{CEsat} = f(T_{vj}), V_{GE} = 15\text{V}$

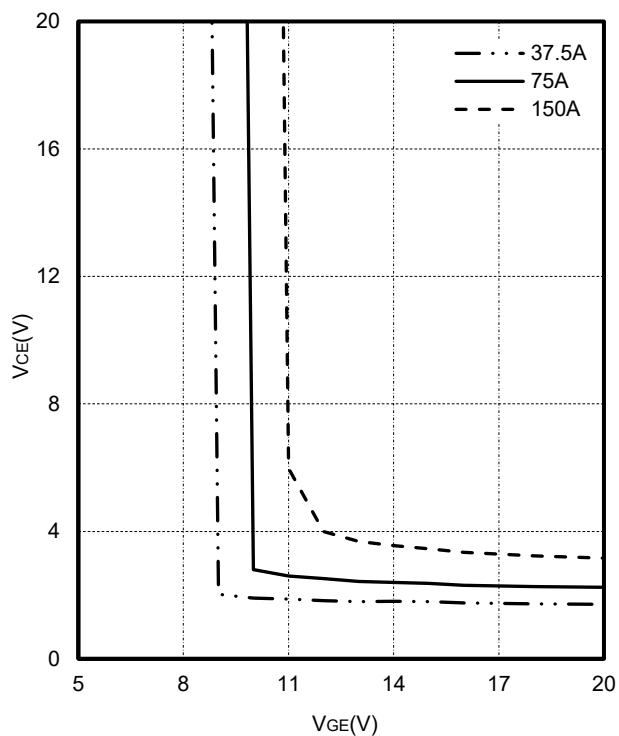


Fig 9. Typical collector-emitter saturation voltage as a function of V_{GE} ($T_j=25^\circ\text{C}$)

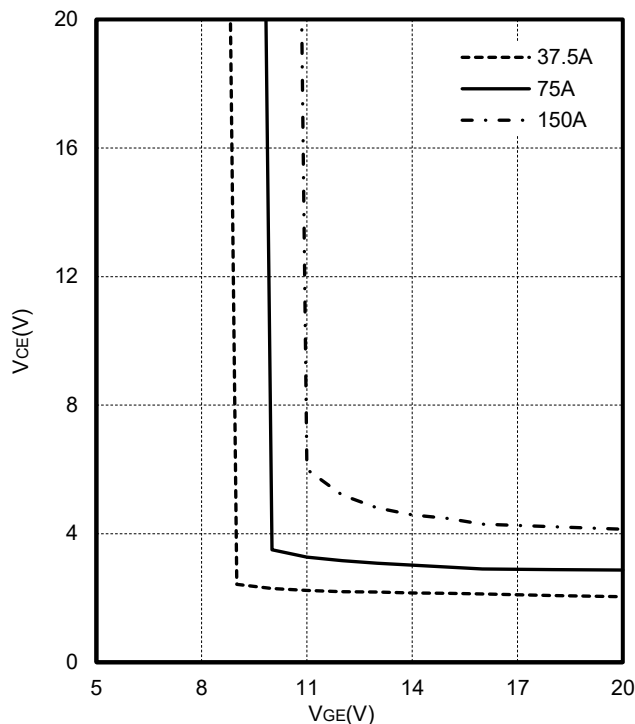


Fig 10. Typical collector-emitter saturation voltage as a function of V_{GE} ($T_j=125^\circ\text{C}$)

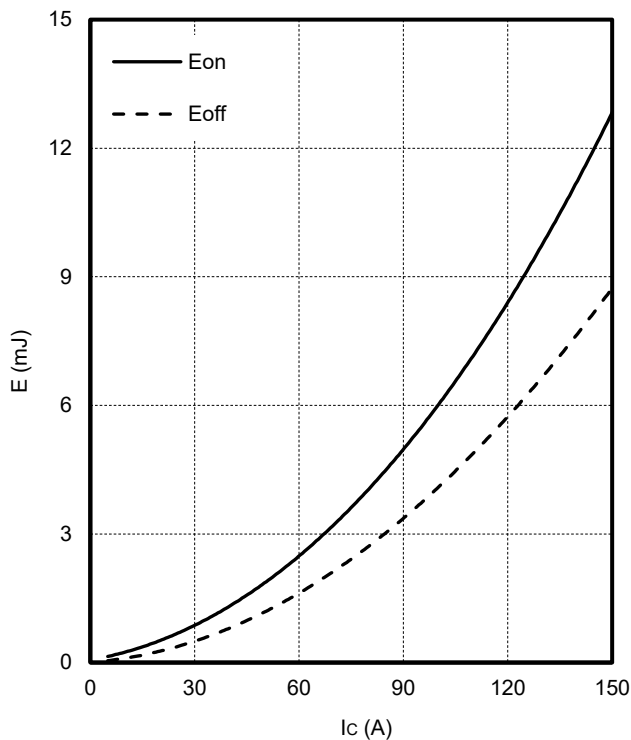


Fig 11. Typical switch energy as a function of I_c (Inductive load, $T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15\text{V}$, $R_g=12\Omega$)

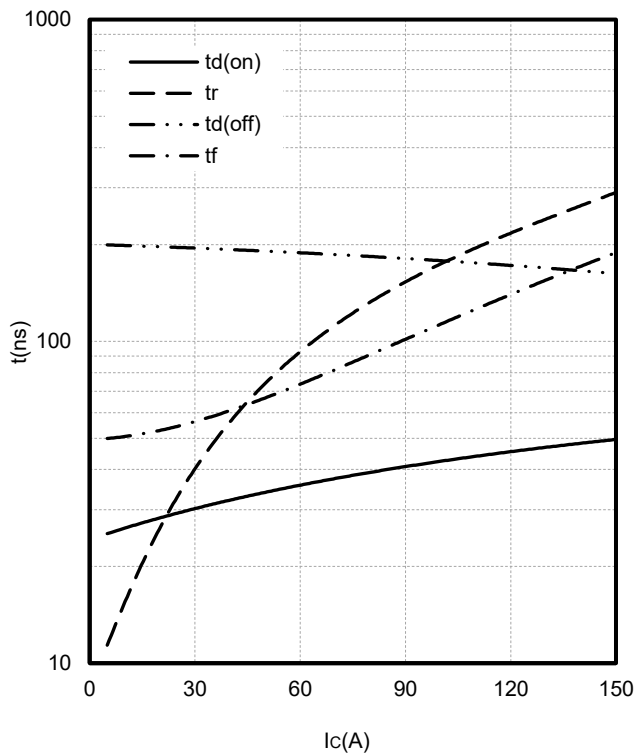


Fig 12. Typical switch time as a function of I_c (Inductive load, $T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15\text{V}$, $R_g=12\Omega$)

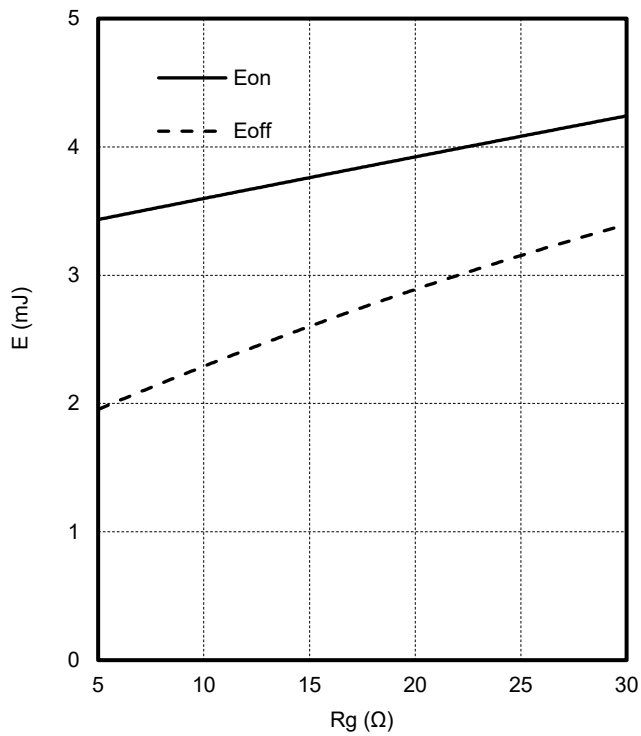


Fig 13. Typical switch energy as a function of Rg (Inductive load, $T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15\text{V}$, $I_c=75\text{A}$)

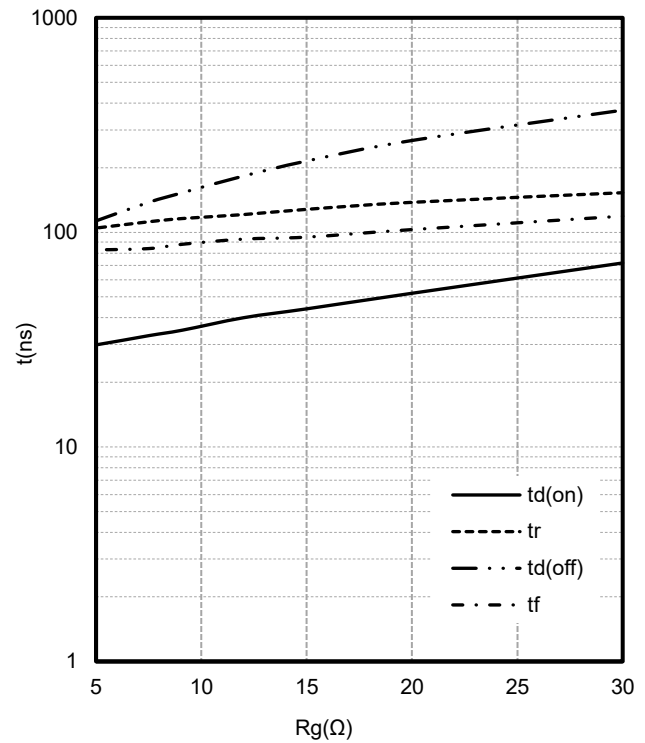


Fig 14. Typical switch time as a function of Rg (Inductive load, $T_j=25^\circ\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=15\text{V}$, $I_c=75\text{A}$)

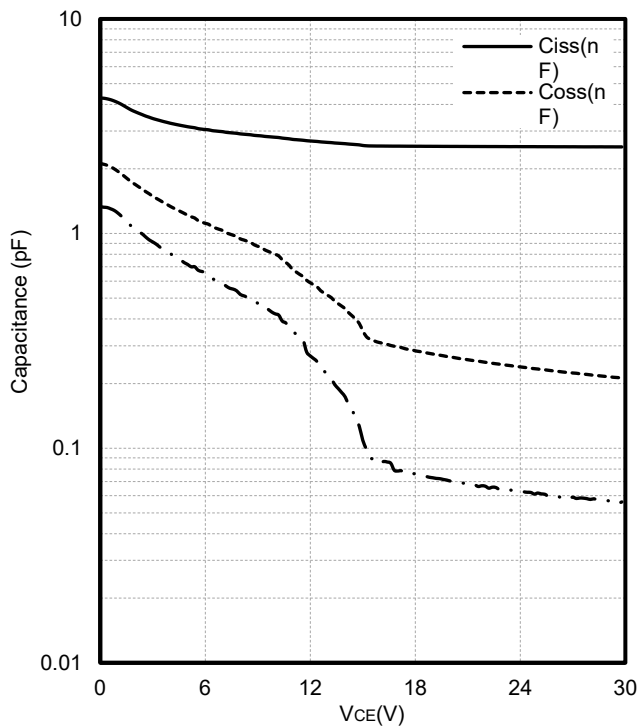


Fig 15. Typical capacitance as a function of collector-emitter voltage ($V_{ge}=0\text{V}$, $f=1\text{MHz}$)

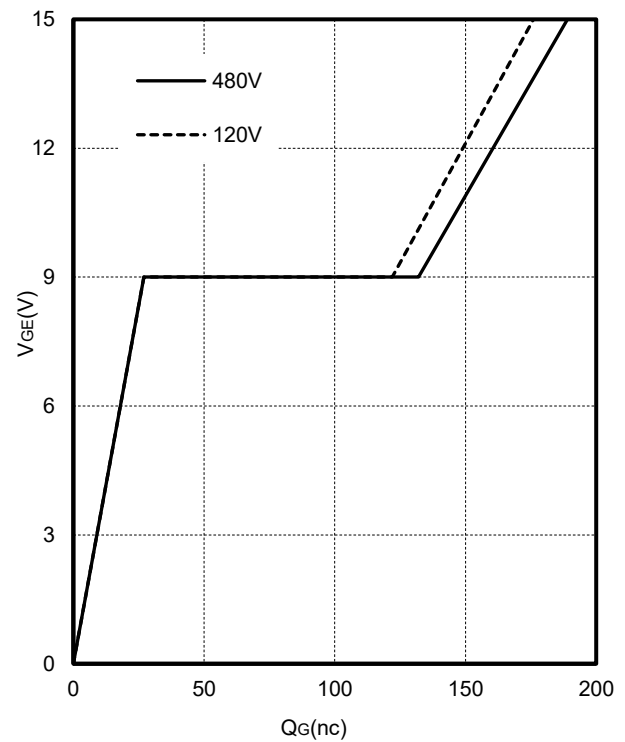


Fig 16. Typical gate charge ($I_c=75\text{A}$)

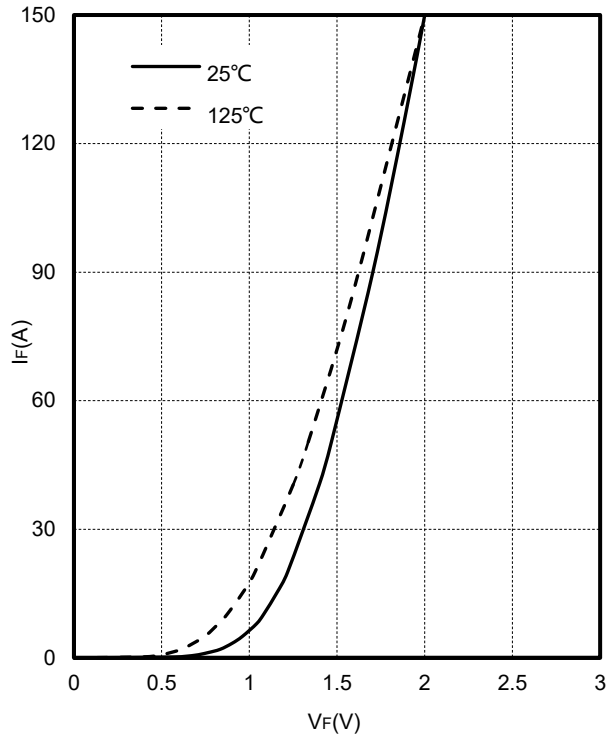


Fig 17. Typical diode forward current as a function of forward voltage

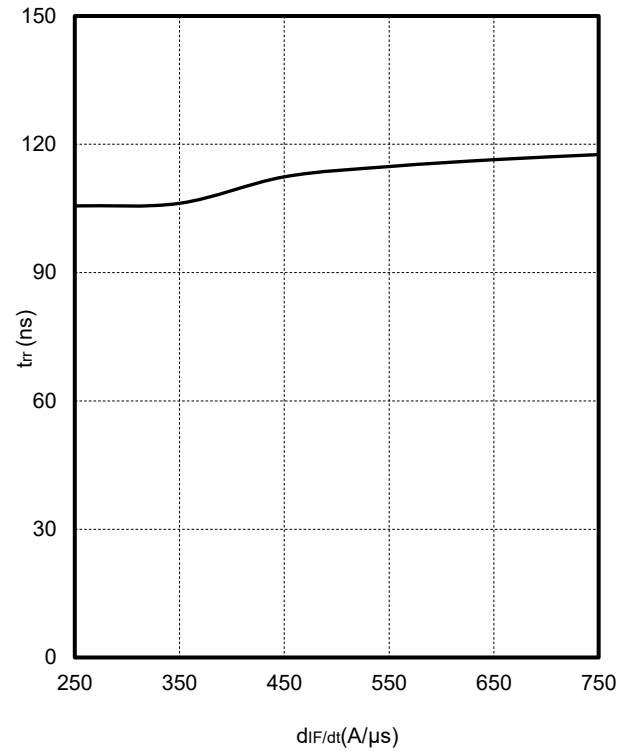


Fig 18. Typical t_{rr} as a function of dI_F/dt , $V_r=400V$, $I_F=75A$, $T_j=25^\circ C$

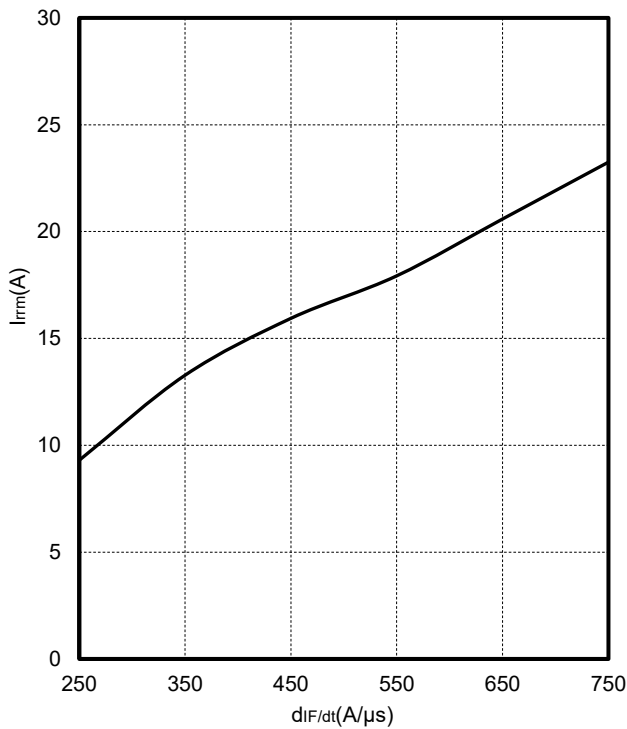


Fig 19. Typical I_{rrm} as a function of dI_F/dt , $V_r=400V$, $I_F=75A$, $T_j=25^\circ C$

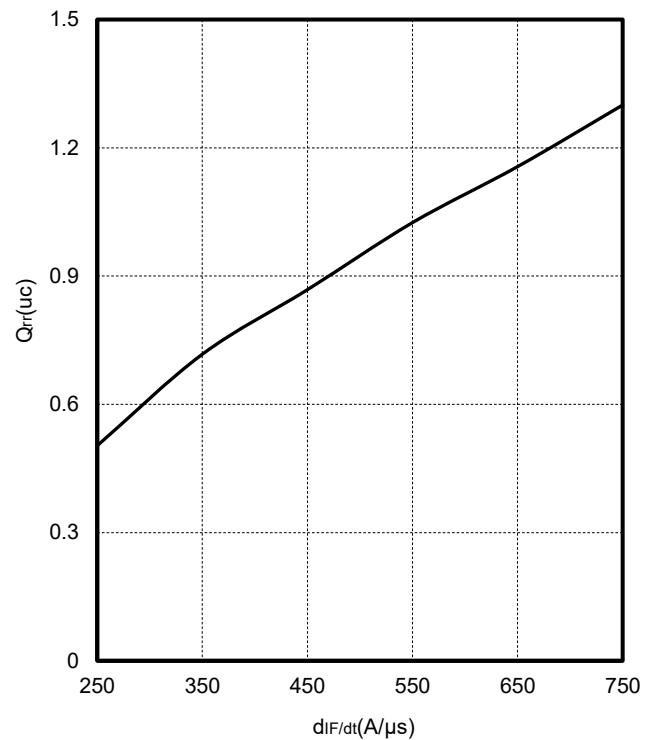


Fig 20. Typical Q_{rr} as a function of dI_F/dt , $V_r=400V$, $I_F=75A$, $T_j=25^\circ C$

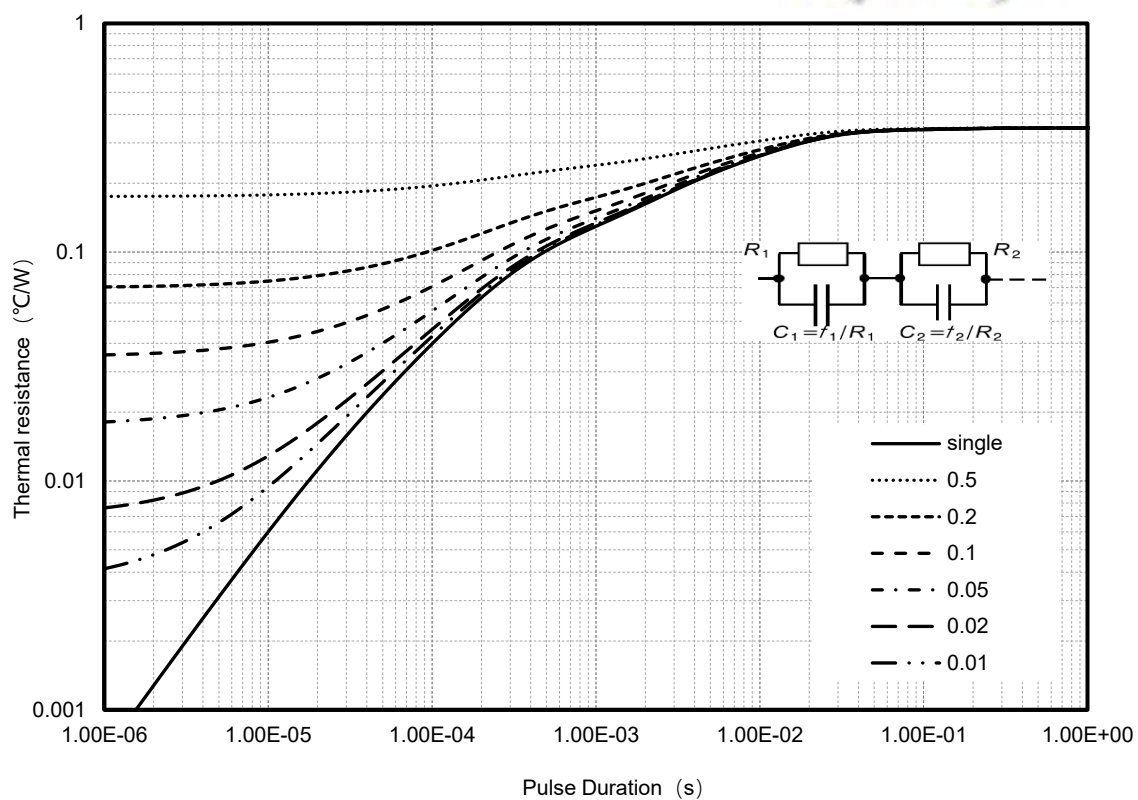
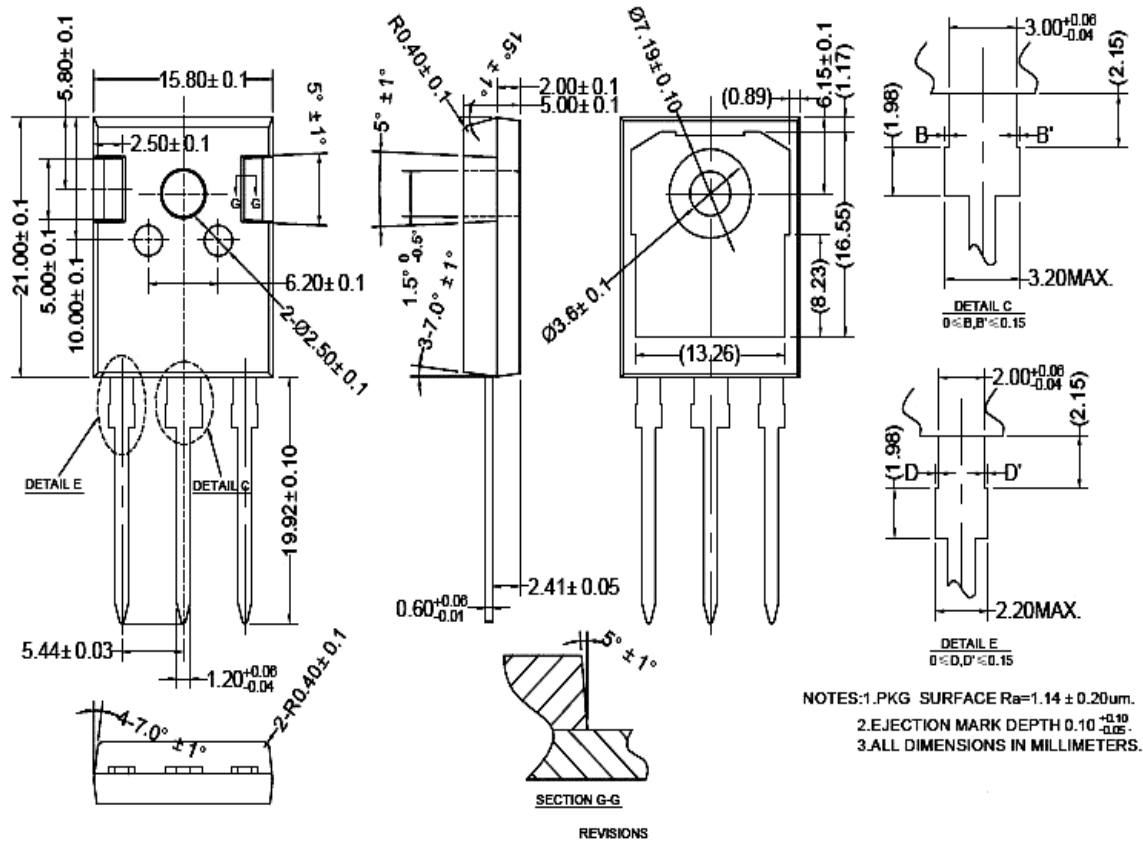


Fig 21. IGBT transient thermal impedance, $Z_{th}=f(t_p), D=t_p/T$



TO247 PACKAGE OUTLINE



NOTES:1.PKG SURFACE Ra=1.14±0.20µm.
2.EJECTION MARK DEPTH 0.10^{+0.10/-0.05}.
3.ALL DIMENSIONS IN MILLIMETERS.

公差标注	公差值	表面粗糙度
0	±0.2	Ra3.2~6.3
0.0	±0.1	Ra1.6~3.2
0.00	±0.01	Ra0.8~1.6
0.000	±0.005	Ra0.4~0.8
0.0000	±0.002	Ra0.2~0.4

0≤D,D'≤0.15

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